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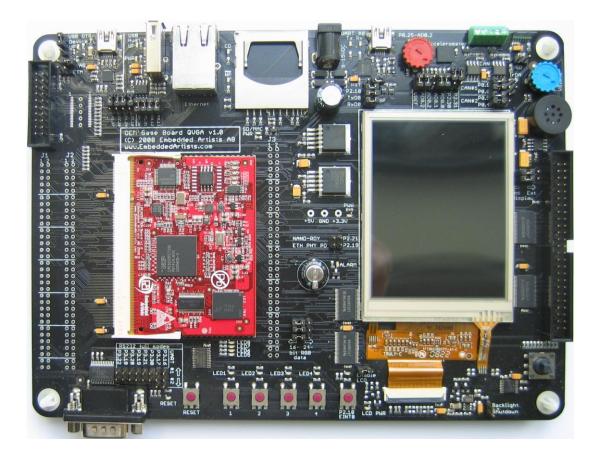
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LPC3250 Developer's Kit - User's Guide

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LPC3250 Developer's Kit User's Guide



Get Up-and-Running Quickly and Start Developing Your Applications On Day 1!



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1 Document Revision History

Revision	Date	Description
A	2009-10-05	First official revision of document
В	2010-10-18	Added section (4.6) about USB device interface.
		Updated rework instruction in section (4.6) for USB device interface and R100.
		Corrected section 5.4.3 about service boot jumpers.
		Updated to rev 1.3 of OEM board schematic.
С	2011-10-26	Updated section 5.4.2 about how to store an application in NAND flash and execute from external memory.
D	2011-12-19	Added note about CE marking.

2 Introduction

Thank you for buying Embedded Artists' *LPC3250 Developer's Kit* based on NXP's ARM926EJ-S LPC3250 microcontroller.

This document is a User's Guide that describes the *LPC3250 OEM Board* and the *QVGA Base Board* hardware design. It is the User's Manual for both the *LPC3250 Developer's Kit* as well as for just the *LPC3250 OEM Board*.

2.1 Features

Embedded Artists' *LPC3250* Developer's Kit with NXP's ARM926EJ-S LPC3250 microcontroller lets you get up-and-running quickly. The small sized OEM board offers many unique features that ease your learning curve and speed up your program development. The board has also been designed for OEM applications with volume discount available. The features of the *LPC3250 OEM Board* are:

- NXP's ARM926EJ-S LPC3250 microcontroller in BGA package, with 256 KByte internal RAM
- External data memory: 64 MB DDR SDRAM (16-bit databus width)
- External FLASH memories: 128 MB (1Gbit) NAND FLASH and 4 MB (32Mbit) SPI-NOR FLASH
- 13.0000 MHz crystal for cpu
- 256 Kbit I2C E2PROM for storing non-volatile parameters
- Buffered 16-bit data bus for external expansion
- 200 pos expansion connector (SODIMM-200 format, 0.6mm pitch)
 - Almost all LPC3250 pins available (except dedicated pins for on-board memories and internal powering)
- 3.15-3.3V powering
- Onboard reset generation
- 5 LEDs
- Compact SODIMM size: 66 x 48 mm
 - Eight layer PCB design for compact design and best noise immunity

There is an accompanying *QVGA Base Board* that can be used for initial prototyping work. This base board was originally developed for the LPC2478 processor and the associated *LPC2478 OEM Board* in SODIMM format. Some interfaces, for example the CAN bus and ETM, do not exist on the LPC3250 and can hence not be used. The features of the *QVGA Base Board* are:

- 3.2 inch QVGA TFT color LCD with touch screen (4-wire version)
 - 18-bit RGB interface to display
- Connectors
 - 200 pos, 0.6mm pitch SODIMM connector for the LPC3250 OEM Board
 - Expansion connector with all LCD controller signals, for custom displays
 - Expansion connector with all SODIMM interface signals
 - Ethernet connector (RJ45)
 - CAN interface & connector (cannot be used with the LPC3250 OEM Board)
 - MMC/SD interface & connector

- JTAG connector
- Pads for ETM connector (cannot be used with the LPC3250 OEM Board)
- Interfaces
 - USB OTG interface & connector
 - USB host interface & connector
 - Full modem RS232 on UART #1 (cannot be used on 32-bit databus cpu boards, but RxD2/TxD2 can alternatively be connected to the RS232 interface)
 - Dual CAN interface & connector (cannot be used with the LPC3250 OEM Board)
 - IrDA transceiver interface
- Power
 - Power supply, either via USB or external 9-15V DC
- Other
 - 5-key joystick
 - 3-axis accelerometer
 - 5 push-button keys (four via I2C and one on 'gpi01/service_n' (P2.10))
 - 9 LEDs (8 via I2C and one on 'gpi01/service_n' (P2.10))
 - Analog input
 - USB-to-serial bridge on UART #5 (FT232R) and ISP functionality
 - Reset push-button and LED
 - 250x150 mm in size

2.2 ESD and Handling Precaution

Please note that the *LPC3250 OEM Board* and *QVGA Base Board* come without any case/box and all components are exposed for finger touches – and therefore extra attention must be paid to ESD (Electro-Static Discharge) precaution.

Make it a habit always to first touch the metal surface of one of the USB or SC/MMC connectors for a few seconds with both hands before touching any other parts of the boards. That way, you will have the same electrical potential as the board and therefore minimize the risk for ESD damages.

Never touch directly on the *LPC3250 OEM Board* and in general as little as possible on the *QVGA Base Board*. The push-buttons on the *QVGA Base Board* have grounded shields to minimize the effect of ESD.

Note that Embedded Artists does not replace boards that have been damaged by ESD.

Do not exercise excessive pressure on the LCD glass area. That will damage the display. Also, do not apply pressure on the two flex cables connecting the LCD. These are relatively sensitive and can be damaged if too much pressure is applied to them.

Note that Embedded Artists does not replace boards where the LCD has been improperly handled.

The core voltage for the LPC3250 can be dynamically changed, via I2C commands sent to the LTC3447 voltage converter. The voltage can be set to up to 2V. Note that this is above the limits of the core voltage. Read the LPC3250 datasheet for details (the absolute maximum core voltage allowed is 1.39V).

Note that Embedded Artists do not replace LPC3250 OEM boards where the core voltage $(V_{DD(CORE)})$ has been raised above 1.39 Volt. It is the user's responsibility not to exceed the voltage specification found in the datasheet.

2.4 CE Assessment

The LPC3250 Developers Kit (consisting of the LPC3250 OEM Board and QVGA Base Board) is CE marked. See separate CE Declaration of Conformity document.

The *LPC3250 Developers Kit* is a class A product. In a domestic environment this product may cause radio interference in which case the user may be required to take adequate measures.

EMC emission test has been performed on the *LPC3250 Developers Kit*. Standard interfaces like Ethernet, USB, serial have been in use. General expansion connectors where internal signals are made available (for example processor pins) have been left unconnected. Connecting other devices to the product via the general expansion connectors may alter EMC emission. It is the user's responsibility to make sure EMC emission limits are not exceeded when connecting other devices to the general expansion connectors of the *LPC3250 Developers Kit*.

Due to the nature of the *LPC3250 Developers Kit* – an evaluation board not for integration into an endproduct – fast transient immunity tests and conducted radio-frequency immunity tests have not been executed. Externally connected cables are assumed to be less than 3 meters. The general expansion connectors where internal signals are made available do not have any other ESD protection than from the chip themselves. Observe ESD precaution.

Note that the *LPC3250 OEM* board is classified as a component and is hence not CE marked separately. It can perform different functions in different integrations and it does not have a direct function. It is therefore not in the scope of the CE Directive. An end product, where an *OEM Board* is integration into, is however very likely to need CE marking.

2.5 Other Products from Embedded Artists

Embedded Artists have a broad range of LPC1xxx/LPC2xxx/LPC3xxx/LPC4xxx based boards that are very low cost and developed for prototyping / development as well as for OEM applications. Modifications for OEM applications can be done easily, even for modest production volumes. Contact Embedded Artists for further information about design and production services.

2.5.1 Design and Production Services

Embedded Artists provide design services for custom designs, either completely new or modification to existing boards. Specific peripherals and I/O can be added easily to different designs, for example, communication interfaces, specific analog or digital I/O, and power supplies. Embedded Artists has a broad, and long, experience in designing industrial electronics in general and with NXP's LPC1xxx/LPC2xxx/LPC3xxx microcontroller family in specific. Our competence also includes wireless and wired communication for embedded systems. For example IEEE802.11b/g (WLAN), Bluetooth[™], ZigBee[™], ISM RF, Ethernet, CAN, RS485, and Fieldbuses.

2.5.2 OEM / Education / QuickStart Boards and Kits

Visit Embedded Artists' home page, www.EmbeddedArtists.com, for information about other OEM / Education / QuickStart boards / kits or contact your local distributor.

3 LPC3250 OEM Board Design

Please read the LPC3250 OEM Board datasheet and associated schematic for information about the board. Some additional information about the LPC3250 OEM Board is presented below.

3.1 LPC3250 OEM Board Schematics

3.1.1 Schematic Page 2: Misc

3.1.1.1 Crystals

The microprocessor crystal frequency is 13.0000 MHz, which is the recommended frequency from NXP. An internal PLL can create many other frequencies from this, like 208 MHz and 266 MHz.

The LPC3250 has an internal real-time clock (RTC) block that can be used to provide real-time and alarm function. A 32.768 kHz crystal gives the base frequency for the RTC. The RTC block can be powered via a separate supply (for example from a battery or high-capacity capacitor). The 32.768 kHz can also be used as main oscillator via a PLL: 32.768 kHz x 397 = 13.009 MHz.

Note that the clocking structure is different from the LPC2xxx family. It is a more complex structure but also much more versatile and flexible. There is no shortcut but to read the LPC3250 User's Manual in detail to understand the options and settings.

3.1.1.2 Booting

The LPC3250 starts executing from an on-chip ROM, containing the bootloader. Note that the LPC3250 does not contain any on-chip FLASH memory. Program code must be loaded from an external source into the on-chip SRAM.

The default boot is from an external memory (see LPC3250 User's Manual for details). Program code is typically stored in NAND or SPI-NOR flash.

By pulling pin GPI_01/SERVICE_N low, UART boot mode is activated. This is a method for downloading code from the PC, for example for programming the bootloader for the first time. Note that pin GPI_01/SERVICE_N can be pulled low by pressing the "P2.10" key on the QVGA Base Board.

3.1.1.3 JTAG interface

The JTAG interface is a standard ARM-compatible JTAG interface.

3.1.1.4 SPI NOR FLASH

There is a 32Mbit (4 MByte) NOR flash connected to the SPI bus. Embedded Artists can choose to mount, either S25FL032P from Spansion, AT45DB321 from Atmel, or other, on the board depending on component availability at the time of production. Mounted chips will be supported by the LPC3250 bootloader. However, commands used to program the memory differ. Chip id should always be read out to determine exact type mounted.

3.1.1.5 Reset Generation

The reset generation is handled by a standard voltage supervisor chip, CAT811R from Catalyst Semiconductor. The reset signal will be held active (i.e., low) until the supply voltages, +3.3V, is within margins (above 2.63V). The reset duration is typically 200 mS (consult the CAT811R datasheet for exact details). The output reset signal is push/pull output that is converted to an open-collector / open-drain output via the 74LVC1G125 buffer. An external reset source can pull the reset signal low (with an open-collector/open-drain output). The RESET_N input on the LPC3250 has a 1.2V voltage range (voltage domain: VDD_RTC). A 74LVC1G125 buffer makes sure this voltage range is not exceeded by the external signal RESET_IN (which has 3.3V range).

3.1.1.6

I2C E2PROM

There is a 256 kbit E²PROM accessible via the I²C interface (I2C1). The LPC3250 has two on-chip I²C communication channels (I2C1 and I2C2). More peripheral units are easily connected to the two-wire I²C bus, just as long as the addresses do not collide. The address of the 256kbit E²PROM is 0xA0, which is also indicated in the schematic.

There are 2.2 kohm pull-up resistors (pull-ups are always needed on I²C busses) on the board on both I²C channels.

3.1.2 Schematic Page 3: Powering

3.1.2.1 1.2V and 1.8V Fixed Voltages

The LPC3250 requires three fixed voltages; 1.2V for the core, 1.8V for the memory interface and 3.15-3.3V for the rest of the i/o interfaces. The 1.2V and 1.8V voltages are generated by two LM3671MF step-down switching regulators from National Semiconductor. These regulators are capable of generating 600mA, which by far exceed the needed current by the LPC3250 and other components on the *LPC3250 OEM Board*. The 3.15-3.3V voltage is the input voltage to the *LPC3250 OEM Board*, see below.

The Real-time clock also needs a 1.2V power, which is generated by a LDO (MIC5232).

3.1.2.2 1.2V Adjustable Core Voltage

The core 1.2V voltage is adjustable and is generated by the step down switching regulator LTC3447 from Linear Technologies. This regulator is capable of generating 600mA, which also by far exceed the needed current by the LPC3250. The adjustment is done via an I2C channel, I2C1 in the LPC3250 case. The core voltage can be adjusted as a power save feature. By lowering the voltage (down to 0.9V), the total power consumption can be lowered but the clock frequency of the core must then also be lowered. This is a trade-off that is important for hand held/portable equipment. *Note that it is the user's responsibility not to program the LTC3447 to generate too high core voltage, which is possible*. The LTC3447 can generate voltages up to 2V, which by far exceed the limits for the LPC3250.

See the LPC3250 datasheet for exact details about voltage ranges, but it is in the region of 1.1-1.39V. Also see the LTC3447 datasheet for details about how to adjust the voltage (it is a write-only register). The I2C address for the LTC3447 is indicated in the schematic.

Note that a core voltage of 1.35V should be programmed when working with the external DDR SDRAM.

3.1.2.3 Input Voltage

The input voltage to the *LPC3250 OEM Board* is given by the requirements of the LPC3250. The recommended input voltage range is 3.15V to 3.3V. The input supply must be stable but there are no special needs for bulk capacitors close to the power pins on the expansion connectors. The needed capacitors are placed close to the switched step down switching regulators on the *LPC3250 OEM Board*.

Note that the *LPC3250 OEM Board* is sensitive to input noise on the input voltage. The peak-to-peak noise should be below 10mV. A linear regulator to feed the input voltage is strongly recommended.

3.1.3 Schematic Page 4: External Memories

Page 4 of the schematic contains the external memory interface and the external memories. The memory interface uses a 16-bit databus and operates at 1.8V level, which minimizes power consumption.

3.1.3.1 DDR SDRAM

A 512 MBit (64 MByte) Mobile DDR SDRAM is used (MT46H32M16LF from Micron). The chip is powered by 1.8V and is organized as 32Mbit x16, i.e. it has 16-bit databus width. The chip is connected to EMC_DYCS0_N (memory bank #0 for dynamic RAM) at address range 0x8000 0000 – 0x9FFF FFFF.

Note that memory bank #1 for dynamic RAM is not available (i.e., signal EMC_DYCS1_N is not used).

3.1.3.2 NAND Flash

A 1 Gbit (128 MByte) NAND flash is used (K9F1G08U0A-P from Samsung). The chip is powered by 3.3V and has 8-bit databus width. The NAND flash builds on a single-level cell (SLC) technology and has a page size of 2112 bytes (2,048 + 64 bytes). Note that the chip is not directly accessible via the memory bus. Instead, all accesses must be done via the on-chip NAND flash controller of the LPC3250.

3.1.3.3 Buffers to External Interface

The LPC3250 memory interface is available on the expansion connector. The data bus width is 16-bits on the external interface. The relevant signals are buffered. The following four static memory regions are available for external access:

- External static bank #0 (0xE000 0000 0xE0FF FFFF) 16-bit databus width and 16MByte in size.
- External static bank #1 (0xE100 0000 0xE1FF FFFF) 16-bit databus width and 16MByte in size.
- External static bank #2 (0xE200 0000 0xE2FF FFFF) 16-bit databus width and 16MByte in size.
- External static bank #3 (0xE300 0000 0xE3FF FFFF) 16-bit databus width and 16MByte in size.

By default (R44 = 0 ohm, R43 not mounted), signal N_ABUF_EN is pulled low and the two buffers for address and control signals (U13 and U14) are enabled and act as output (from the *LPC3250 OEM Board*).

The buffered version of the LPC3250 signal OE controls the direction of the data bus buffer (U15). During read operations the buffer acts as an input and during write operations it acts as an output. The data bus buffer is controlled by the signals BLS0 and BLS1, each controlling lower and upper bytes of the 16-bit databus. These signals are active when accessing the external static memory regions.

The buffers are dual voltage buffers and act as level translators between the internal 1.8V signal levels and the external levels. Connect the external bus voltage to VDD_EXT. See the datasheet of 74AVCA164245 for exact details about voltage range. Normally 3.3V powering is used on the external side.

3.1.4 Schematic Page 5: Digital and Analog IO

Page 5 of the schematic contains all digital and analog signals plus three LEDs controlled by signals P2.10 - P2.12.

3.1.5 Schematic Page 6: Ethernet Interface

An external PHY (DP83848 from National Semiconductor) implements a 100/10Mbps Ethernet interface. The external PHY is connected to the Ethernet MAC on the LPC3250 via the RMII interface.

3.1.6 Schematic Page 7: USB Interface

There is a USB 2.0 (OTG, Host, Device) interface on the LPC3250. An external PHY (ISP1301) is needed for the cpu.

3.1.7 Schematic Page 8: Expansion Connector

The *LPC3250 OEM Board* integrates the core part of a typical LPC3250 board design with a reasonable large amount of external memories. All relevant signals of LPC3250 are available on the 200 pos, 0.6mm pitch expansion connector (SODIMM-200 format). See the next section for a detailed list of available pins.

3.2 Usage of CPU Pins

Almost all pins of the LPC3250 are directly available on the expansion connectors. Only in a few cases pins are used for dedicated functionality like (dynamic) memory control signals, chip select signals and power supply. Such pins are not available on the expansion connector. The table below lists all pins and their possible restrictions.

Pin	Available on expansion connector
ADIN0 (TS_XM) ADIN1 (TS_YM) ADIN2 (TS_AUX_IN) TS_XOUT TS_YOUT	Yes
I2C1_SCL I2C1_SDA I2C2_SCL I2C2_SDA	Yes, but I2C-E2PROM (U5 – 24LC256) and core voltage generator (U7, LTC3447) connected to I2C1 pins. Note that these signals have 2.2K pull-up resistors.
SPI1_CLK / SCK0 SPI1_DATIO / MOSI0 / MCFB2 SPI1_DATIN / MISO0 / GPI_25 / MCFB1 GPI0_05 / SSEL0 / MCFB0	Yes, but note that SPI NOR flash is connected to these signals.
HIGHCORE / LCDVD[17] ONSW	Yes Note that HIGHCORE signal can control adjustable core voltage of R28 mounted (normally not mounted).
I2S1TX_CLK / MAT3.0 I2S1TX_SDA / MAT3.1 I2S1TX_WS / CAP3.0 MS_BS / MAT2.1 MS_DIO0 / MAT0.0 MS_DIO2 / MAT0.1 MS_DIO2 / MAT0.2 MS_DIO3 / MAT0.3 MS_SCLK / MAT2.0 P0.0 / I2S1RX_CLK P0.1 / I2S1RX_WS P0.2 / I2S0RX_SDA / LCDVD[4] P0.3 / I2S0RX_CLK / LCDVD[5] P0.4 / I2S0RX_WS / LCDVD[6] P0.5 / I2S0TX_SDA / LCDVD[7] P0.6 / I2S0TX_CLK / LCDVD[12] P0.7 / I2S0TX_WS / LCDVD[13] PWM_OUT1 / LCDVD[16] PWM_OUT2 / LCDVD[19] SPI2_CLK / SCK1 / LCDVD[23] SPI2_DATIN / MISO1 / LCDVD[21] / GPI_27	 Yes Note: Pull-up on GPI_01/SERVICE_N GPO_01 and GPO_14 controls LED1/LED2 GPI_03 has pull-down resistor GPI_05 has pull-down resistor GPI_28 has pull-up resistor U7_HCTS/CAP0.1/LCDCLKIN/ GPI_22 has pull-up resistor GPO_19 controls NAND write protect signal

SPI2_DATIO / MOSI1 / LCDVD[20]	
SYSCLKEN / LCDVD[15]	
TST_CLK2	
U1_RX / CAP1.0 / GPI_15	
U1_TX	
U2_HCTS / U3_CTS / GPI_16	
U2_RX / U3_DSR / GPI_17	
U2_TX / U3_DTR	
U3_RX / GPI_18	
U3_TX	
U5_RX / GPI_20	
U6_IRRX / GPI_21	
U6_IRTX	
U7_HCTS / CAP0.1 / LCDCLKIN / GPI_22	
U7_RX / CAP0.0 / LCDVD[10] / GPI_23	
U7_TX / MAT1.1 / LCDVD[11]	
GPI_00 / I2S1RX_SDA	
GPI_01 / SERVICE_N	
GPI_02 / CAP2.0 / ENET_RXD3	
GPI_03	
GPI_04 / SPI1_BUSY	
GPI 05 / U3 DC	
GPI_06 / HSTIM_CAP / ENET_RXD2	
GPI 07 / CAP4.0 / MCABORT	
GPI_08 / KEY_COL6 / SPI2_BUSY / ENET_RX_DV	
GPI_09 / KEY_COL7 / ENET_COL	
GPI_19 / U4_RX	
GPI_28 / U3_RI	
GPIO_00	
GPIO_01	
GPIO_04 / SSEL1 / LCDVD[22]	
GPO_00 / TST_CLK1	
GPO_01	
GPO_02 / MAT1.0 / LCDVD[0]	
GPO_03 / LCDVD[1]	
GPO_04	
GPO 05	
GPO_06 / LCDVD[18]	
GPO_07 / LCDVD[2]	
GPO_08 / LCDVD[8]	
GPO_09 / LCDVD[9]	
GPO_10 / MC2B / LCDPWR	
GPO_12 / MC2A / LCDLE	
GPO_13 / MC1B / LCDDCLK	
GP0_14	
GPO_15 / MC1A / LCDFP	
GPO_16 / MC0B / LCDENAB / LCDM	
GPO_17	
GPO_18 / MC0A / LCDLP	
GPO_19	
GPO_20	
GPO_21 / U4_TX / LCDVD[3]	
GPO_22 / U7_HRTS / LCDVD[14]	
GPO_23 / U2_HRTS / U3_RTS	
EMC_D19/P2.0	Yes
EMC_D20/P2.1	Note that signals can only be D2 signals, not
EMC_D21/P2.2	Note that signals can only be P2 signals, not

EMC_D22/P2.3 EMC_D23/P2.4 EMC_D24/P2.5 EMC_D25/P2.6 EMC_D26/P2.7 EMC_D27/P2.8 EMC_D28/P2.9 EMC_D29/P2.10 EMC_D30/P2.11 EMC_D31/P2.12	 EMC databus. P2.10 controls LED3 P2.11 controls LED4 P2.12 controls LED5 No, connected to on-board USB transceiver,
USB_ATX_INT_N USB_DAT_VP / U5_RX USB_I2C_SCL USB_I2C_SDA USB_OE_TP_N USB_SE0_ VM / U5_TX	ISP1301
KEY_COL1 / ENET_RX_CLK / ENET_REF_CLK KEY_COL2 / ENET_RX_ER KEY_COL3 / ENET_CRS KEY_COL4 / ENET_RXD0 KEY_COL5 / ENET_RXD1 KEY_ROW3 / ENET_TX_EN KEY_ROW4 / ENET_TXD0 KEY_ROW5 / ENET_TXD1 GPIO_02 / KEY_ROW6 / ENET_MDC GPIO_03 / KEY_ROW7 / ENET_MDIO	No, connected to on-board Ethernet PHY, DP83848
EMC_A00 – EMC_A23	Yes, but only available via the address bus buffer
EMC_D00 – EMC_D15	Yes, but only available via the data bus buffer
EMC_BLS0 EMC_BLS1 EMC_CS0_N EMC_CS1_N EMC_CS2_N EMC_CS3_N EMC_OE_N EMC_WR_N	Yes, but only available via the buffer
FLASH_ALE FLASH_CE_N FLASH_IO00 – FLASH_IO07 FLASH_RD_N FLASH_RDY FLASH_WR_N	No, used for on-board NAND flash memory.
EMC_CAS_N EMC_CKE0 EMC_CLK EMC_DQM0 EMC_DQM1 EMC_DYCS0_N EMC_RAS_N EMC_D16/EMC_DQS0 EMC_D17/EMC_DQS1 EMC_D18/EMC_CLK_N	No, used for on-board DDR SDRAM.

EMC_BLS2 EMC_BLS3 EMC_CKE1 EMC_CLKIN EMC_DQM2 EMC_DQM3 EMC_DYCS1_N	No. These signals are not used and not available.
KEY_COL0 / ENET_TX_CLK KEY_ROW0 / ENET_TX_ER KEY_ROW1 / ENET_TXD2 KEY_ROW2 / ENET_TXD3	 No. These signals are not used and not available. Note that three (of four) signals can become available if 0 ohm resistors are mounted: KEYROW0, mount R93 KEYROW1, mount R94 KEYCOL0, mount R91
JTAG signals	Yes
RESET_N RESOUT_N	Yes Note pull-up resistor on RESET_IN and internal open-drain driving of RESET_IN
RTCX_IN RTCX_OUT SYSX_IN SYSX_OUT	No, directly connected to on-board crystals
All VDD and VSS pins	No, not directly accessible, but ground is available and 3.15-3.3V input voltage
PLL397_LOOP	No, internal on-board connection to signal.

The QVGA Base Board illustrates how to typically connect external interfaces (like USB, external memory devices, etc) to the LPC3250 OEM Board. Study this schematic (also found in this document) for details.

3.3 LPC3250 OEM Board Mechanical Dimensions and Connector

Figure 1 below contains a drawing of the board that includes mechanical measures. See SODIMM-200 standard for exact measures. 1.8V keying is used (SODIMM-200 boards are either 1.8V or 2.5V keyed).

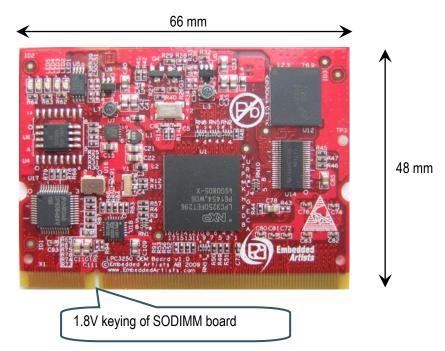


Figure 1 – LPC3152 OEM Board Mechanical Dimensions

The SODIMM-200 format is a standard and there are many connectors that are suitable from many different manufactures. The many sources also keep the connector cost very low. Note that the connector should be 1.8V keyed.

One suitable connector is 0-1473005-4 from Tyco/AMP. Basically any SODIMM, DDR2, 200pos, 1.8V, right-angled connector will do.

3.4 Things to note about the LPC3250 OEM Board

3.4.1 LPC3250 Adjustable Core Voltage

The core voltage for the LPC3250 is adjustable via I2C commands sent to the LTC3447 voltage converter. The core voltage should always be increased to 1.35 volt in order for external mobile DDR SDRAM to function properly. Initialization code that increase the adjustable core voltage to 1.35V can be downloaded from Embedded Artists support pages.

Note that it is the user's responsibility not to program the LTC3447 to generate too high core voltage, which is possible. The LTC3447 can generate voltages up to 2V, which by far exceed the limits for the LPC3250.

3.4.2 NAND FLASH Bad Block

The NAND Flash is the K9F1G08U0A from Samsung and has 1 GBit capacity. The chip may include invalid blocks when shipped from factory. A maximum of 20 invalid blocks may exist initially, i.e., 1004-1024 valid blocks. Additional invalid blocks may develop while being used. Invalid blocks are defined as blocks that contain one or more bad bits. Do not erase or program factory-marked bad blocks. More information about appropriate management of invalid blocks can be found in technical notes and datasheet from Samsung.

3.4.3 Brand of Memory Chips

Note that there is no guarantee for a certain brand or version of memory chips; SPI-NOR flash, parallel NAND flash and mobile DDR SDRAM. The lifetime of memory chips is limited and availability can also be limited from time to time. Embedded Artists make every effort to mount the original design chip on the board. In case that is impossible a compatible chip will instead be mounted without any prior notice. There can be small programming differences between mounted brands. The application

The support page contains datasheets to the different memory devices and information about mounted devices on different board versions.

3.4.4 LPC3250 Peripherals

The key scan interface peripheral cannot be used with the LPC3250 OEM Board because the Ethernet interface is active.

4 QVGA Base Board Design

Please read the QVGA Base Board schematic for information about the board. Some additional information about the QVGA Base Board is presented below.

4.1 QVGA Base Board Schematics

The QVGA Base Board contains a number of interfaces and connectors to the LPC3250 OEM Board. The design can be viewed as a reference schematic for custom designs around the LPC3250 OEM Board.

4.2 Signal Mapping to QVGA Base Board

The QVGA Base Board was originally developed for the LPC2478 processor and the associated LPC2478 OEM Board in SODIMM format. The silk screen on the base board therefore reflects the LPC2478 signal names.

The table below lists differences between the LPC3250 and LPC2478 OEM Boards in their SODIMM interface. The table also lists what functionality that is connected to the different signals.

SODIMM pin number	LPC2478 OEM Board	LPC3250 OEM Board	QVGA Base Board	Comment
1	ETH_TXP	ETH_TXP	Ethernet i/f	
2	ETH_RXP	ETH_RXP	Ethernet i/f	
3	ETH_TXN	ETH_TXN	Ethernet i/f	
4	ETH_RXN	ETH_RXN	Ethernet i/f	
5	ETH_VDD	ETH_VDD	Ethernet i/f	
6	ETH_GND	ETH_GND	Ethernet i/f	
7	ETH_LED1	ETH_LED1	Ethernet i/f	
8	ETH_LED2	ETH_LED2	Ethernet i/f	
9	VBAT_IN	VBAT_IN	0.33F backup cap on vbat signal	
10	ALARM	ONSW	Connected to alarm-LED (active high)	ONSW functionality not demonstrated/ supported on <i>QVGA Base Board</i> .
11	RESET_IN	RESET_IN	Connects to RESET push-button and USB-to- serial bridge (for automatic ISP functionality)	
12	RESET_OUT	RESET_OUT	Connects to RESET LED indicator.	
			Used to reset PCA9532 and QVGA display.	
13	ETH_PHY_PD	ETH_PHY_PD	Part of Ethernet i/f, can be connected to SODIMM pin 118	
14	JTAG_DBGEN	JTAG_DBGEN	Connected to 'JTAG Enable' jumper	
15	JTAG_TCK	JTAG_TCK	Connected to standard 20 pos (2x10 pin) JTAG connector	
16	JTAG_RTCK	JTAG_RTCK	Connected to standard 20 pos (2x10 pin) JTAG connector	
17	JTAG_NTRST	JTAG_NTRST	Connected to standard 20 pos (2x10 pin) JTAG connector	
18	JTAG_TMS	JTAG_TMS	Connected to standard 20 pos (2x10 pin)	

			JTAG connector	
19	JTAG_TDI	JTAG_TDI	Connected to standard 20 pos (2x10 pin) JTAG connector	
20	JTAG_TDO	JTAG_TDO	Connected to standard 20 pos (2x10 pin) JTAG connector	
21	V3A	VDDA	Positive reference for trimming potentiometer	
22	VREF	NC (can be VCCA)	Can be connected VDDA(V3A)	
23	VSSA	VSSA	Negative reference for trimming potentiometer	
24	GND	GND	GND	
25	P2.0	GPO_10	LCDPWR signal, power enable for QVGA display. Also connects to ETM pads, if connector mounted.	ETM cannot be used
26	P2.1	GPO_12	LCDLE signal. Not used by design. Also connects to ETM pads, if connector mounted.	ETM cannot be used
27	P2.2	GPO_13	LCDDCLK signal, dot clock for QVGA display. Also connects to ETM pads, if connector mounted.	ETM cannot be used
28	P2.3	GPO_15	LCDFP signal, vsync for QVGA display. Also connects to ETM pads, if connector mounted.	ETM cannot be used
29	P2.4	GPO_16	LCDENAB signal, data enable for QVGA display. Also connects to ETM pads, if connector mounted.	ETM cannot be used
30	P2.5	GPO_18	LCDLP signal, hsync for QVGA display. Also connects to ETM pads, if connector mounted.	ETM cannot be used
31	P2.6	P0.2	LCD databit 4. Also connects to ETM pads, if connector mounted.	ETM cannot be used
32	P2.7	P0.3	LCD databit 5. Also connects to ETM pads, if connector mounted.	ETM cannot be used
33	P2.8	P0.4	LCD databit 6. Also connects to ETM pads, if connector mounted.	ETM cannot be used
34	P2.9	P0.5	LCD databit 7. Also connects to ETM pads, if connector mounted.	ETM cannot be used
35	P2.10	GPI_01	Connected to push-button (for enabling bootloader during reset or EINT0 input). Also connects to LED (active low). Connects to USB-to-serial bridge (for	Enable UART booting by pulling signal low at reset
			automatic ISP functionality)	
36	P2.11	U7_HCTS	LCDCLKIN, an external clock signal can be feed to this pin.	
37	VCC	VCC		
38	GND	GND		
39	VCC	VCC		
40	GND	GND		
41	P0.29-USBA-DP	NC (can be KEYROW0)	Connects to USB device/OTG interface	USB Device/OTG i/f not used
42	P0.31-USBB-DP	USB_CONN_DP	Connects to USB host interface	USB Host interface is connected to the LPC3250

Connects to USB device/OTG interface

USB Device/OTG

43

P0.30-USBA-DM

NC (can be

		KEYROW1)		i/f not used
44	USBB-DM	USB_CONN_DN	Connects to USB host interface	USB Host interface is connected to the LPC3250
45	P2.12	GPO_06	LCD databit 18	
46	P2.13	PWMOUT2	LCD databit 19	
47	P0.0	U6_IRTX	Can be connected to RD1 for CAN channel #1, can also connect to IrDA transceiver	CAN interface cannot be used by the LPC3250.
				IrDA can be used
48	P0.1	U6_IRRX	Can be connected to TD1 for CAN channel #1, can also connect to IrDA transceiver	CAN interface cannot be used by the LPC3250.
				IrDA can be used
49	P0.2	U5_TX	Can be connected to USB-to-serial bridge (TxD on UART #5. Note that the silk screen text says UART#0)	Possible to boot over UART#5
50	P0.3	U5_RX	Can be connected to USB-to-serial bridge (RxD on UART #5. Note that the silk screen text says UART#0)	Possible to boot over UART#5
51	P0.4	GPO_02	LCD databit 0, can also be connected to RD2 for CAN channel #2	CAN i/f cannot be used
52	P0.5	GPO_03	LCD databit 1, can also be connected to TD2 for CAN channel #2	CAN i/f cannot be used
53	P0.6	GPO_08	LCD databit 8	
54	P0.7	GPO_09	LCD databit 9	
55	P0.8	PWMOUT1	LCD databit 16	
56	P0.9	HICORE	LCD databit 17	
57	P0.10	U1_TX	Can be connected to RS232 interface (TxD)	
58	P0.11	U1_RX	Can be connected to RS232 interface (RxD)	
59	P0.12	USB_VBUS_CTRL	Can be connected to enable USB-host power switch	
60	P0.13	GPO_17	Can be connected to LED (active low) for USB-host indicator	
61	P0.14	GPO_20	Can be connected to USB-device enable- device signal	
62	P0.15	SPI1_CLK	QVGA display and Touch screen serial interface (SPI-SCK)	
63	P0.16	GPO_04	QVGA display serial interface (SSEL)	
64	P0.17	SPI1_DATIN	QVGA display and Touch screen serial interface (SPI-MISO)	
65	P0.18	SPI1_DATIO	QVGA display and Touch screen serial interface (SPI-MOSI)	
66	P0.19	GPO_05	QVGA display serial interface (command/data select)	
67	P0.20	GPO_11	Touch screen serial interface (SSEL)	
68	P0.21	TS_XP	No special usage on QVGA Base Board	
69	P0.22	TS_YP	No special usage on QVGA Base Board	

70 71 72

73 74

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96

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98

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100

NAND_FLASH_R

DY

GPO_19

 P0.23	AIN0	Can be connected to accelerometer, X-axis	
 P0.24	AIN1	Can be connected to accelerometer, Y-axis	
 P0.25	AIN2	Can be connected to accelerometer, Z-axis, or analog input (trimpot)	
 P0.26	GPO_00	Connects to speaker output on AOUT signal	
 P0.27-SDA0	I2C1_SDA	I2C-SDA0, connects to PCA9532 (IO expander)	
P0.28-SCL0	I2C1_SCL	I2C-SCL0, connects to PCA9532 (IO expander)	
GND	GND		
GND	GND		
P1.2	MCICLK	Connects to MCICLK on SD/MMC connector	
P1.3	MCICMD	Connects to MCICMD on SD/MMC connector	
P1.5	GPO_01	Connects to MCIPWR on SD/MMC connector	
P1.6	MCIDAT0	Connects to MCIDAT0 on SD/MMC connector	
P1.7	MCIDAT1	Connects to MCIDAT1 on SD/MMC connector	
P1.11	MCIDAT2	Connects to MCIDAT2 on SD/MMC connector	
P1.12	MCIDAT3	Connects to MCIDAT3 on SD/MMC connector	
P1.13	GPIO_05	No special usage on QVGA Base Board	
 P1.18	GPO_14	Connects to QVGA backlight control. Can also be connected to LED (active low) to be used for USB device/OTG	USB Device/OTG i/f not used
P1.19	GPI_13	No special usage on QVGA Base Board	
P1.20	U7_RX	LCD databit 10	
P1.21	U7_TX	LCD databit 11	
P1.22	P0.6	LCD databit 12	
P1.23	P0.7	LCD databit 13	
P1.24	GP0_22	LCD databit 14	
P1.25	SYSCLKEN	LCD databit 15	
P1.26	SPI2_DATIO	LCD databit 20	
 P1.27	SPI2_DATIN	LCD databit 21, can also be connected to ISP1301 (USB OTG transceiver)	ISP1301 on base board shall not be used
P1.28	GPIO_04	LCD databit 22, can also be connected to ISP1301 (USB OTG transceiver)	ISP1301 on base board shall not be used
P1.29	SPI2_CLK	LCD databit 23, can also be connected to ISP1301 (USB OTG transceiver)	ISP1301 on base board shall not be used
P1.30	USB_CONN_VBUS	Can be connected to VBUS signal from USB host power	
P1.31	GPI_02	Can be connected to over-current error signal from USB host power switch	

Can be connected to SODIMM pin 119

Signal not used.

Exist internally on OEM board.

GND

GND

101

101	0112	0115		
102	GND	GND		
103	NC	I2S1TX_CLK		
104	NC	I2S1TX_SDA		
105	NC	I2S1TX_WS		
106	NC	P0.0		
107	NC	P0.1		
108	NC	GPI_00		
109	NC	I2C2_SDA		
110	NC	I2C2_SCL		
111	NC	GPI_04		
112	NC	GPI_06		
113	NC	USB_CONN_ID		
114	NC	POWER_ON		
115	NC	TST_CLK2		
116	P2.14	P2.7	Can connect as enable signal for IrDA transceiver (active low)	
117	P2.15	GPIO_00	Can connect to interrupt signal from touch screen controller	
118	P2.19	GPIO_01	Can be connected to Ethernet PHY PD signal, SODIMM pin 13	
119	P2.21	GPI_07	Can be connected to NAND FLASH busy output, SODIMM pin 100	
120	P2.22	P2.0	Connects to joystick switch	
121	P2.23	P2.1	Connects to joystick switch	
122	P2.25	P2.2	Connects to joystick switch	
123	P2.26	P2.3	Connects to joystick switch	
124	P2.27	P2.4	Connects to joystick switch	
125	P2.30	P2.5	Can control sensitivity of accelerometer	
126	P2.31	P2.6	Can control sensitivity of accelerometer	
127	P4.48	GPO_07	LCD databit 2	
128	P4.29	GP0_21	LCD databit 3	
129	GND	GND		
130	GND	GND		
131	BA15	BA15	No special usage on QVGA Base Board	
132	BDQM1	BCS3	No special usage on QVGA Base Board	
133	BA14	BA14	No special usage on QVGA Base Board	
134	BDQM0	BCS2	No special usage on QVGA Base Board	
135	BA13	BA13	No special usage on QVGA Base Board	
136	BCAS	BCS1	No special usage on QVGA Base Board	
137	BA12	BA12	No special usage on QVGA Base Board	
138	BRAS	BCS0	No special usage on QVGA Base Board	

	-			
139	BA11	BA11	No special usage on QVGA Base Board	
140	BBLS1	BBLS1	No special usage on QVGA Base Board	
141	BA10	BA10	No special usage on QVGA Base Board	
142	BBLS0	BBLS0	No special usage on QVGA Base Board	
143	BA9	BA9	No special usage on QVGA Base Board	
144	BWE	BWE	No special usage on QVGA Base Board	
145	BA8	BA8	No special usage on QVGA Base Board	
146	BOE	BOE	No special usage on QVGA Base Board	
147	BA7	BA7	No special usage on QVGA Base Board	
148	BA23	BA23	No special usage on QVGA Base Board	
149	BA6	BA6	No special usage on QVGA Base Board	
150	BA22	BA22	No special usage on QVGA Base Board	
151	BA5	BA5	No special usage on QVGA Base Board	
152	BA21	BA21	No special usage on QVGA Base Board	
153	BA4	BA4	No special usage on QVGA Base Board	
154	BA20	BA20	No special usage on QVGA Base Board	
155	BA3	BA3	No special usage on QVGA Base Board	
156	BA19	BA19	No special usage on QVGA Base Board	
157	BA2	BA2	No special usage on QVGA Base Board	
158	BA18	BA18	No special usage on QVGA Base Board	
159	BA1	BA1	No special usage on QVGA Base Board	
160	BA17	BA17	No special usage on QVGA Base Board	
161	BA0	BA0	No special usage on QVGA Base Board	
162	BA16	BA16	No special usage on QVGA Base Board	
163	DBUS_EN	NC (can connect to KEYCOL0)		
164	ABUF_EN	ABUF_EN		
165	VCC	VDD_EXT		
166	GND	GND		
167	BD15	BD15	Occupied by 16-bit databus. No special usage on QVGA Base Board	
168	BD31/P3.31	GPI_08	No special usage on QVGA Base Board	
169	BD14	BD14	Occupied by 16-bit databus. No special usage on QVGA Base Board	
170	BD30/P3.30	GP0_23	No special usage on QVGA Base Board.	
171	BD13	BD13	Occupied by 16-bit databus. No special usage on QVGA Base Board	
172	BD29/P3.29	GPI_09	No special usage on QVGA Base Board	
173	BD12	BD12	Occupied by 16-bit databus. No special usage on QVGA Base Board	
174	BD28/P3.28	GPI_19	No special usage on QVGA Base Board	
175	BD11	BD11	Occupied by 16-bit databus. No special usage on QVGA Base Board	

176	BD27/P3.27	P2.8	No special usage on QVGA Base Board
177	BD10	BD10	Occupied by 16-bit databus. No special usage on QVGA Base Board
178	BD26/P3.26	P2.9	No special usage on QVGA Base Board
179	BD9	BD9	Occupied by 16-bit databus. No special usage on QVGA Base Board
180	BD25/P3.25	P2.10	No special usage on QVGA Base Board
181	BD8	BD8	Occupied by 16-bit databus. No special usage on QVGA Base Board
182	BD24/P3.24	P2.11	No special usage on QVGA Base Board
183	BD7	BD7	Occupied by 16-bit databus. No special usage on QVGA Base Board
184	BD23/P3.23	P2.12	No special usage on QVGA Base Board
185	BD6	BD6	Occupied by 16-bit databus. No special usage on QVGA Base Board
186	BD22/P3.22	GPI_28	No special usage on QVGA Base Board.
187	BD5	BD5	Occupied by 16-bit databus. No special usage on QVGA Base Board
188	BD21/P3.21	U2_TX	No special usage on QVGA Base Board.
189	BD4	BD4	Occupied by 16-bit databus. No special usage on QVGA Base Board
190	BD20/P3.20	U2_RX	No special usage on QVGA Base Board.
191	BD3	BD3	Occupied by 16-bit databus. No special usage on QVGA Base Board
192	BD19/P3.19	GPI_05	No special usage on QVGA Base Board.
193	BD2	BD2	Occupied by 16-bit databus. No special usage on QVGA Base Board
194	BD18/P3.18	U2_CTS	No special usage on QVGA Base Board.
195	BD1	BD1	Occupied by 16-bit databus. No special usage on QVGA Base Board
196	BD17/P3.17	U3_RX	Can be connected to RS232 interface
197	BD0	BD0	Occupied by 16-bit databus. No special usage on QVGA Base Board
198	BD16/P3.16	U3_TX	Can be connected to RS232 interface
199	VCC	VDD_EXT	
200	GND	GND	

4.3 Jumpers

The QVGA Base Board has a number of jumpers in order to be able to connect/disconnect and fully utilize all functionality of the LPC3250 and the boards. Figure 2 illustrates all jumpers and explains to what part of the design they belong.

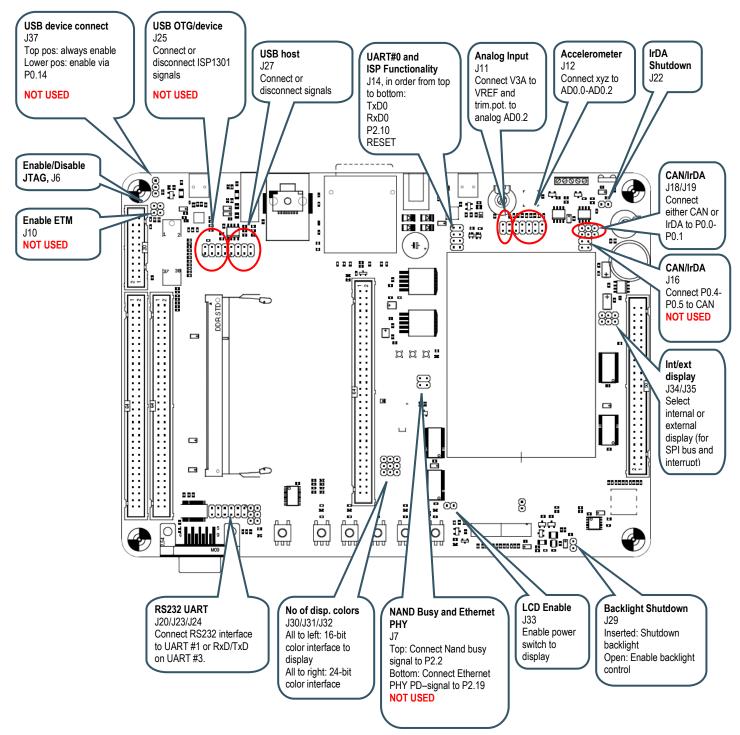


Figure 2 – QVGA Base Board Jumpers